



| 製品名称<br>Product Name       |                                      |                          | 製品型番<br>Material Number |                     |
|----------------------------|--------------------------------------|--------------------------|-------------------------|---------------------|
| プラグ アセンブリ<br>Plug Assembly | 嵌合高さ<br>Stacking Height<br>H=7,13mm  | 吸着カバー無し<br>Without Cover | 無鉛<br>LEAD FREE         | 5 3 4 8 1 - * * 6 7 |
|                            |                                      | 吸着カバー無し<br>Without Cover | 無鉛<br>LEAD FREE         | 5 3 4 8 1 - * * 7 7 |
|                            |                                      | 吸着カバー付き<br>With Cover    | 無鉛<br>LEAD FREE         | 5 3 6 2 5 - * * 7 2 |
|                            | 嵌合高さ<br>Stacking Height<br>H=8,14mm  | 吸着カバー無し<br>Without Cover | 無鉛<br>LEAD FREE         | 5 3 5 5 1 - * * 7 7 |
|                            |                                      | 吸着カバー付き<br>With Cover    | 無鉛<br>LEAD FREE         | 5 3 6 4 7 - * * * 9 |
|                            | 嵌合高さ<br>Stacking Height<br>H=9,15mm  | 吸着カバー付き<br>With Cover    | 無鉛<br>LEAD FREE         | 5 3 6 4 9 - * * 7 2 |
|                            | 嵌合高さ<br>Stacking Height<br>H=10,16mm | 吸着カバー無し<br>Without Cover | 無鉛<br>LEAD FREE         | 5 3 5 5 3 - * * 7 7 |
|                            |                                      | 吸着カバー付き<br>With Cover    | 無鉛<br>LEAD FREE         | 5 3 6 2 7 - * * 7 2 |

\* : 図面参照 Refer to the drawing

- \* \* 6 8 : 吸着カバー無しエンボス梱包  
EMBOSSED PACKAGING OF PRODUCT WITHOUT COVER
- \* \* 7 4 : 吸着カバー付きエンボス梱包  
EMBOSSED PACKAGING OF PRODUCT WITH COVER
- \* \* 7 5 : 吸着カバー付きスティック梱包  
STICK PACKAGING OF PRODUCT WITH COVER
- \* \* 7 6 : 吸着カバー無しトレイ梱包  
TRAY PACKAGING OF PRODUCT WITHOUT COVER  
5 3 5 5 1 - \* \* 7 7 のトレイ梱包品は、5 3 9 3 6 - \* \* 7 6 です。
- \* \* 7 8 : 吸着カバー無しエンボス梱包  
EMBOSSED PACKAGING OF PRODUCT WITHOUT COVER  
5 2 7 6 0 - \* \* 7 0 のエンボス梱包品は、5 4 9 1 4 - \* \* 7 8 です。
- \* \* 7 9 : 吸着カバー無しスティック梱包  
STICK PACKAGING OF PRODUCT WITHOUT COVER
- \* \* 9 4 : 吸着カバー付きエンボス梱包  
EMBOSSED PACKAGING OF PRODUCT WITH COVER

|  |                   |   |                  |
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| <b>K</b>                               | SEE SHEET 1 OF 13 | 0.635 mm PITCH B TO B CONN.<br>HOUSING ASSEMBLY<br>-LEAD FREE- <b>製品仕様書</b> |                  |
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【3. 定格 RATINGS】

| 項目<br>Item   | 規格<br>Standard   |                  |
|--|------------------|------------------|
| 最大許容電圧<br>Rated Voltage (MAXIMUM)                                    | 100 V            | [AC(実効値 rms)/DC] |
| 最大許容電流<br>Rated Current (MAXIMUM)                                    | 0.5 A            |                  |
| 使用温度範囲<br>Ambient Temperature Range<br>(Operating and Non-operating) | -55°C ~+105°C *1 |                  |

\* 1 : 通電による温度上昇分を含む。  
Including terminal temperature rise

【4. 性能 PERFORMANCE】

4-1. 電気的性能 Electrical Performance

| 項目<br>Item                             | 条件<br>Test Condition  | 嵌合高さ<br>Stacking Height | 規格<br>Requirement   |
|--|---|-------------------------|---------------------|
| 4-1-1<br>接触抵抗<br>Contact Resistance    | 適合するコネクタを嵌合させ、開放電圧 20mV 以下、短絡電流 10mA以下にて測定する。<br>(JIS C5402 5.4)<br><br>Mate applicable connectors, measure by dry circuit, 20mV MAXIMUM, 10mA MAXIMUM.<br>(JIS C5402 5.4)  | H= 4 - 7mm              | 40 milliohm MAXIMUM |
|  |   | H= 8 -10mm              | 50 milliohm MAXIMUM |
|  |   | H= 11 -13mm             | 60 milliohm MAXIMUM |
|  |   | H= 14 -16mm             | 70 milliohm MAXIMUM |
| 4-1-2<br>絶縁抵抗<br>Insulation Resistance | 適合するコネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、DC 250V を印加し測定する。<br>(JIS C5402 5.2/MIL-STD-202 試験法 302)<br><br>Mate applicable connectors together and apply 250V DC between adjacent terminal and ground.<br>(JIS C5402 5.2/MIL-STD-202 Method 302) | 1000 Megohm MINIMUM     |                     |

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| 項目<br>Item                          | 条件<br>Test Condition  | 嵌合高さ<br>Stacking Height | 規格<br>Requirement      |
|-------------------------------------|---|-------------------------|------------------------|
| 4-1-3<br>耐電圧<br>Dielectric Strength | 適合するコネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、AC 250V (実効値) を 1分間 印加する。<br>(JIS C5402 5.1/MIL-STD-202 試験法 301)<br><br>Mate applicable connectors, apply 250V AC for 1 minute between adjacent terminal or ground.<br>(JIS C5402 5.1/MIL-STD-202 Method 301) |                         | 異状なきこと<br>No Breakdown |

4-2. 機械的性能 Mechanical Performance

| 項目<br>Item  | 条件<br>Test Condition   | 規格<br>Requirement  |
|---|--|--|
| 4-2-1<br>挿入・抜去力<br>Insertion Force/<br>Withdrawal Force | 毎分 25±3 mm の速さで挿入、<br>抜去を行う。   | 挿入力<br>Insertion Force<br>0.690N {70gf} / CIRCUIT<br>MAXIMUM   |
|   | Insert and withdraw connectors,<br>at a rate of 25±3mm/minute.   | 抜去力<br>Withdrawal Force<br>0.118N {12gf} / CIRCUIT<br>MINIMUM  |
| 4-2-2<br>ターミナル保持力<br>Terminal Pull-out<br>Force         | ハウジングに装着されたターミナルを<br>毎分 25±3mm の速さで引っ張る。<br><br>Apply axial pull out force on the terminal<br>assembled in the housing at a rate of 25±3mm/<br>minute. | 52760-**70<br>52885-**72<br>52837-**70<br>52901-**72<br>55091-**71<br>55091-**72<br>53481-**67<br>53481-**77<br>53625-**72<br>53551-**77<br>53647-***9<br>53649-**72<br>53553-**77<br>53627-**72<br><br>1.96 N { 0.2kgf }<br>MINIMUM |

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4-3. その他 Environmental Performance and Others

| 項目<br>Item |                                     | 条件<br>Test Condition  | 規格<br>Requirement             |   |
|------------|-------------------------------------|---|-------------------------------|---|
| 4-3-1      | 繰返し挿抜<br>Repeated<br>Mate / Un-mate | 1分間に 10回以下の速さで挿入、抜去を<br>50回 繰り返す。<br>When mate / un-mated up to 50 cycles<br>repeatedly at a rate of 10 cycles / minute.  | 接触抵抗<br>Contact<br>Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
| 4-3-2      | 温度上昇<br>Temperature Rise            | 適合するコネクタを嵌合させ、最大許容電流<br>を通電し、コネクタの温度上昇分を測定する。<br>(UL 498)<br>Mate applicable connectors and measure the<br>temperature rise of contact when the<br>maximum AC rated current is passed.<br>(UL 498)  | 温度上昇<br>Temperature<br>Rise   | 30°C MAXIMUM  |
| 4-3-3      | 耐振動性<br>Vibration                   | DC 1mA 通電状態にて、嵌合軸を含む互いに<br>垂直な3方向に掃引割合 10~55~10Hz/分、<br>全振幅 1.5mm の振動を 各2時間 加える。<br>(MIL-STD-202試験法 201)<br>Mate connectors and subject to the following<br>vibration conditions, for a period of 2 hours in<br>each of 3 mutually perpendicular axes,<br>passing DC 1mA during the test.<br>Amplitude : 1.5mm P-P<br>Frequency : 10-55-10Hz<br>(MIL-STD-202, Method 201) | 外観<br>Appearance              | 異常なきこと<br>No Damage   |
|            |                                     |   | 接触抵抗<br>Contact<br>Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
|            |                                     |   | 瞬断<br>Discontinuity           | 0.1 microsecond<br>MAXIMUM  |

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| 項目<br>Item |                        | 条件<br>Test Condition  | 規格<br>Requirement          |   |
|------------|------------------------|---|----------------------------|---|
| 4-3-4      | 耐衝撃性<br>Shock          | DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 6方向 に、パルス幅 11ms 衝撃波形が正弦半波 490m/s <sup>2</sup> {50G} の衝撃を 各3回 加える。<br>(JIS C60068-2-27/MIL-STD-202 試験法 213)<br><br>Mate applicable connectors and subject to the following shock conditions. 3 times of shocks shall be applied for each 6 directions along 3 mutually perpendicular axes, passing DC 1mA current during the test.<br>(Total of 18 shocks)<br>Test pulse : Half Sine<br>Peak value : 490m/s <sup>2</sup> {50G}<br>Duration : 11ms<br>(JIS C60068-2-27/MIL-STD-202 Method 213) | 外観<br>Appearance           | 異常なきこと<br>No Damage   |
|            |                        |   | 接触抵抗<br>Contact Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
|            |                        |   | 瞬断<br>Discontinuity        | 0.1 microsecond<br>MAXIMUM  |
| 4-3-5      | 耐熱性<br>Heat Resistance | 適合するコネクタを嵌合させ、105±2℃ の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。<br>(JIS C60068-2-2/MIL-STD-202 試験法 108 )<br><br>Mate applicable connectors and expose to 105±2℃ for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>(JIS C60068-2-2/MIL-STD-202 Method 108)  | 外観<br>Appearance           | 異常なきこと<br>No Damage   |
|            |                        |   | 接触抵抗<br>Contact Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
| 4-3-6      | 耐寒性<br>Cold Resistance | 適合するコネクタを嵌合させ、-55±3℃ の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。<br>( JIS C60068-2-1 )<br><br>Mate applicable connectors and expose to -55±3℃ for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br>( JIS C60068-2-1 )  | 外観<br>Appearance           | 異常なきこと<br>No Damage   |
|            |                        |   | 接触抵抗<br>Contact Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |

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| 項目<br>Item |                               | 条件<br>Test Condition  | 規格<br>Requirement             |   |
|------------|-------------------------------|---|-------------------------------|---|
| 4-3-7      | 耐湿性<br>Humidity               | <p>適合するコネクタを嵌合させ、60±2℃、相対湿度 90～95% の雰囲気中に 96時間 放置後、取り出し、1～2時間 室温に放置する。<br/>(JIS C60068-2-3/MIL-STD-202 試験法103)</p> <p>Mate applicable connectors and expose to 60±2℃, relative humidity 90 to 95% for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br/>(JIS C60068-2-3/MIL-STD-202 Method 103)</p>   | 外 観<br>Appearance             | 異常なきこと<br>No Damage   |
|            |                               |   | 接触抵抗<br>Contact Resistance    | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
|            |                               |   | 耐 電 圧<br>Dielectric Strength  | 4-1-3項<br>満足のこと<br>Must meet 4-1-3  |
|            |                               |   | 絶縁抵抗<br>Insulation Resistance | 100 Megohm<br>MINIMUM   |
| 4-3-8      | 温度サイクル<br>Temperature Cycling | <p>適合するコネクタを嵌合させ、-55±3℃ に 30分、+85±2℃ に 30分、これを 1サイクルとし、5サイクル 繰り返す。但し、温度移行時間は、3分以内 とする。試験後 1～2時間 室温に放置する。<br/>(JISC0025)</p> <p>Mate applicable connectors and subject to the following conditions for 5 cycles. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed.<br/>1 cycle<br/>a) -55±3℃ 30 minutes<br/>b) +85±2℃ 30 minutes<br/>(Transit time shall be within 3 minutes)<br/>(JISC0025)</p> | 外 観<br>Appearance             | 異常なきこと<br>No Damage   |
|            |                               |   | 接触抵抗<br>Contact Resistance    | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |

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| 項目<br>Item |                              | 条件<br>Test Condition   | 規格<br>Requirement          |   |
|------------|------------------------------|--|----------------------------|---|
| 4-3-9      | 塩水噴霧<br>Salt Spray           | <p>適合するコネクタを嵌合させ、35±2℃にて、重量比 5±1% の塩水を 48±4時間 噴霧し、試験後常温で水洗いした後、室温で乾燥させる。<br/>(JIS C60068-2-11/MIL-STD-202 試験法101)</p> <p>Mate applicable connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water, after which the specified measurements shall be performed.<br/>NaCl solution<br/>Concentration: 5±1 %<br/>Spray time: 48±4 hours<br/>Ambient temperature:35±2℃<br/>(JIS C60068-2-11/MIL-STD-202 Method 101)</p> | 外 観<br>Appearance          | 異常なきこと<br>No Damage   |
|            |                              |  | 接触抵抗<br>Contact Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
| 4-3-10     | 亜硫酸ガス<br>SO <sub>2</sub> Gas | <p>適合するコネクタを嵌合させ、40±2℃にて、50±5ppm の亜硫酸ガス中に 24時間 放置する。<br/>Mate applicable connectors and expose to 50±5ppm SO<sub>2</sub> gas, ambient temperature 40±2℃ for 24 hours.</p>  | 外 観<br>Appearance          | 異常なきこと<br>No Damage   |
|            |                              |  | 接触抵抗<br>Contact Resistance | 初期規格値からの<br>変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
| 4-3-11     | 半田付け性<br>Solder-ability      | <p>端子先端より 0.5mm の位置まで 245±3℃の半田に3±0.5秒 浸す。<br/>Dip soldertails into the molten solder {held at 245±3℃} up to 0.5mm from the bottom of the housing for 3±0.5 seconds.</p>   | 濡れ性<br>Solder Wetting      | 浸漬面積の<br>95%以上<br>95% of immersed<br>area must show no<br>voids, pin holes                          |

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|-------------|--|--|--------------------|------------------------------------|
| 4-3-12      | 半田耐熱性<br>Resistance to<br>Soldering Heat | (リフロー時)<br>第6項の条件にて、2回リフローを行う。<br>(When reflowing)<br>Repeat paragraph 6, two times.   | 外 観<br>Appearance  | 端子ガタ<br>割れ等<br>異状無きこと<br>No Damage |
|             |  | (手半田)<br>端子先端より 0.5mm、金具先端より 0.5mm<br>の位置まで 370~400℃ の半田ゴテにて<br>最大5秒 加熱する。<br>(Soldering iron method)<br>0.5mm from terminal tip and fitting nail tip.<br>Soldering time : 5 seconds MAX.<br>Solder temperature : 370~400℃ |                    |                                    |

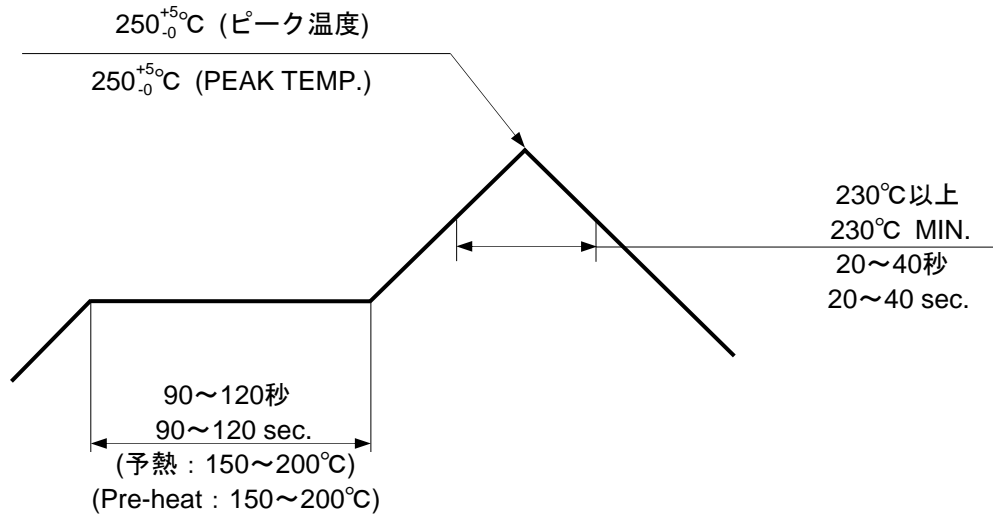
( ) : 参考規格 Reference Standard  
{ } : 参考単位 Reference Unit

【5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS】

図面参照 Refer to the drawing.

|                       |                   |   |                   |
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【6. 赤外線リフロー条件 INFRARED REFLOW CONDITION】



温度条件グラフ  
(温度は基板パターン面)

TEMPERATURE CONDITION GRAPH  
(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記 ; 本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、事前にリフロー評価の確認をお願い致します。

NOTE ; Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C.Boards, and so on.

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【7. 取り扱いの注意事項 INSTRUCTION UPON USAGE】

- 1.実装性能(平坦度)は、実装基板の反りの影響を含まないものと致します。基板の反りはコネクタ両端部を基準とし、コネクタ中央部にて Max0.02mmとして下さい。  
The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. The warpage of the printed circuit board should be a maximum of 0.02mm if measuring from one connector edge to the other.
- 2.本製品の一般性能確認はリジット基板にて実施おります。フレキシブル基板等の特殊な基板へ実装する場合は、事前に実装確認等を行った上でご使用願います。  
The product performance was tested using rigid printed circuit board. In case the product needs to be reflowed onto flexible circuit board, please conduct a reflow test on the flexible circuit board in advance.
- 3.フレキシブル基板に実装する場合は、基板の変形を防止するため、補強板をご使用願います。  
Please add a stiffener on the flexible printed circuit (FPC) when you mount the connector onto FPC in order to prevent deformation of the FPC.
- 4.リフロー条件によっては、樹脂部の変色や端子めつき部にヨリが発生する場合がありますが、製品性能に影響はございません。  
Depending on the reflow conditions, there may be the possibility of a color change in the housing. However, this color change does not have any effect on the product's performance.
5. 半田実装部の未半田は、ターミナル脱落、ピン間ショート、ターミナル座屈、またコネクタの基板からの外れが懸念されます。従って全てのターミナルテール部及び、ネイル部に半田付けを行って下さい。  
If you leave any soldering area on this product open, there may be the possibility of a missing terminal short circuiting between pins, terminal buckling or the potential for the connector to come off of the printed circuit board. Therefore, please solder all of the terminals and fitting nails on the printed circuit board.
- 6.コネクタの性能を損なう恐れがある為、コネクタの洗浄は、行わないで下さい。  
Please do not conduct any "washing process" on the connector because it may damage the product's function.
- 7.実装後において半田ごてによる手修正を行う際は、必ず仕様書掲載の条件以内で行って下さい。  
条件を超えて実施した場合、端子の抜け、接点ギャップの変化、モールドの変形、熔融等、破損の原因になります。  
When conducting manual repairs using a soldering iron, please follow the soldering conditions shown in the product specification. If the conditions in the product spec are not followed, it may cause the terminals to fall off, a change in the contact gap, a deformation of the housing, melting of the housing, and damage the connector.

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|--|-------------------|--|-------------------|
| REVISE ON PC ONLY                      |                   | TITLE:   |                   |
| <b>K</b>                               | SEE SHEET 1 OF 13 | 0.635 mm PITCH B TO B CONN.<br>HOUSING ASSEMBLY<br><b>-LEAD FREE-</b> <b>製品仕様書</b>                                     |                   |
| REV.                                   | DESCRIPTION       | THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION |                   |
| DOCUMENT NUMBER<br><b>PS-52760-015</b> |                   | FILE NAME<br>PS-52760-015.docx   | SHEET<br>11 OF 13 |
| EN-037(2013-04 rev.1)                  |                   |  |                   |

8. 半田こてによる手修正を行なう際、過度の半田やフラックスを使用しないで下さい。半田上がりやフラックス上がりにより接触、機能不良に至る場合があります。

When conducting manual repairs using a soldering iron, please do not use more solder and flux than needed.

This may cause solder wicking and flux wicking issues, and it will eventually cause a contact defect and functional issues.

9. 本製品のエンボス梱包品は紙リールのものがあります。取扱いにご注意下さい。

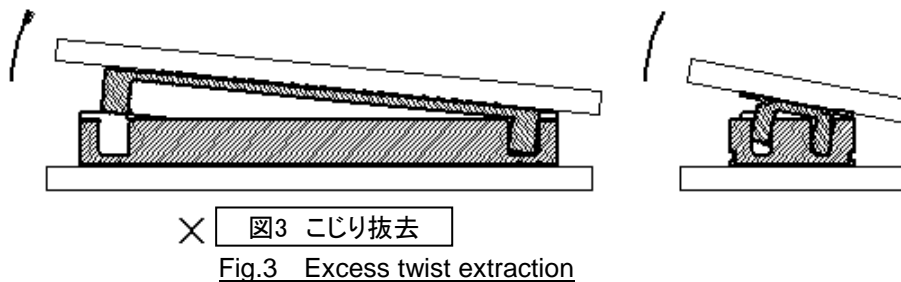
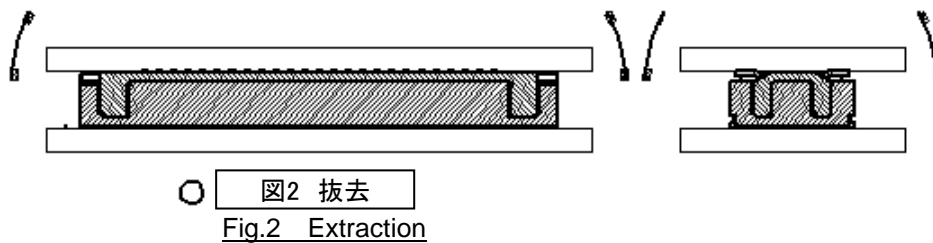
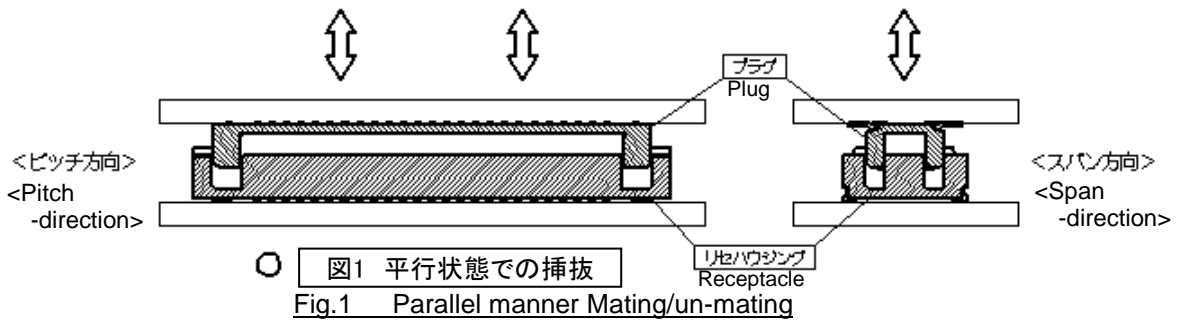
In embossed package, paper reel product exists. Please be very careful upon usage.

10. 抜去は極力嵌合軸に沿って平行に行ってください。(図1)または、左右に少しづつ振りながら行って下さい。(図2) 過度のこじり抜去には注意して下さい。過度のこじり抜去ではコネクタが破壊する可能性があります。(図3)

Please mate the connector horizontally along the mating direction shown below. (See figure 1)

Please align the connector by lightly shaking it from side to side. (See figure 2)

Please be very careful when extracting the connector at an angle. This may cause damage to the connector.



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| REVISE ON PC ONLY                      |                   | TITLE:  |  |
| <b>K</b>                               | SEE SHEET 1 OF 13 | 0.635 mm PITCH B TO B CONN.<br>HOUSING ASSEMBLY<br>-LEAD FREE- <b>製品仕様書</b> |  |
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# molex PRODUCT SPECIFICATION

LANGUAGE

JAPANESE  
ENGLISH

| REV. | REV. RECORD | DATE       | ECN NO.    | WRITTEN BY : | CHECKED BY : |
|------|-------------|------------|------------|--------------|--------------|
| A    | RELEASED    | '04/03/01  | J2004-2758 | N.AIDA       | K.TOJO       |
| B    | REVISED     | '04/04/23  | J2004-3983 | E.SUZUKI     | K.TOJO       |
| C    | REVISED     | '05/01/19  | J2005-2076 | N.AIDA       | K.TOJO       |
| D    | REVISED     | '05/02/24  | J2005-2773 | N.AIDA       | K.TOJO       |
| E    | REVISED     | '07/10/16  | J2008-1357 | R.TSURUOKA   | T.HARUYAMA   |
| F    | REVISED     | '11/10/27  | J2012-0609 | T.KAIHO      | T.ASAKAWA    |
| G    | REVISED     | '13/09/20  | J2014-0524 | Y.SATO06     | T.ASAKAWA    |
| H    | REVISED     | '14/08/04  | J2015-0176 | N.NAITO      | T.ASAKAWA    |
| J    | REVISED     | '14/08/14  | J2015-0230 | N.NAITO      | T.ASAKAWA    |
| K    | REVISED     | 2015/01/20 | J2015-0948 | Y.SATO06     | T.ASAKAWA    |
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| <b>K</b>                 | SEE SHEET 1 OF 13  |  |
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